

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application. Please cancel claims 2-9 and add new claims 10-14 without prejudice or disclaimer.

1. (Currently amended) ~~A miniaturised surface mount~~ An optoelectronic component based on a surface mount technology, said optoelectronic component comprising:

an electrically conductive ~~material (1), the said material is used as a base-~~  
~~material~~ frame to form a base for an assembly;

at least ~~[[an]] one~~ optoelectronic chip ~~(3), the said optoelectronic chip (3) is~~  
mounted on ~~[[the]]~~ said base; ~~[[and]]~~

an electrical connection between ~~[[the]]~~ said optoelectronic chip ~~[(3)]~~ and ~~[[the]]~~  
said electrically conductive ~~material (1)~~ frame by ~~[[a]]~~ wiring means ~~[(6)]~~; and

soldering terminals which are part of said electrically conductive frame and are  
exposed at bottom and side portions of said component;

wherein ~~[[the]]~~ ~~said base-material~~ electrically conductive frame is encapsulated  
with a ~~hard transparent or translucent resin~~ material ~~[(4)]~~ to enable optical radiation to  
be transmitted or received via ~~[[the]]~~ said optoelectronic component~~[[.]]~~; and

wherein said soldering terminals do not extend beyond an outline of said  
encapsulation material.

2-9. (Canceled)

10. (New) The optoelectronic component as claimed in claim 1, wherein said electrically conductive frame is made of a metal.
11. (New) The optoelectronic component as claimed in claim 1, wherein a lens structure is incorporated as part of said encapsulation material.
12. (New) The optoelectronic component as claimed in claim 1, wherein a multiple lens structure is incorporated as part of said encapsulation material.
13. (New) The optoelectronic component as claimed in claim 1, wherein a cavity is formed within said electrically conductive frame and is used to attach said optoelectronic chip within said cavity and serve as a reflector.
14. (New) The optoelectronic component as claimed in claim 1, wherein said electrically conductive frame is crafted with a series of grooves and wings to enhance anchorage and minimize an occurrence of de-lamination.